

Sr. No.	Tender Section & Clause No. & Pg. No., if any	Tender Clause / Topic	Query of the firm	Reply
5)	Annexure -IV	Consortium Agreement Point 3- Role of Parties	evidence of compliance with these requirements is required to be submitted along with the PQB bid or during RFQ We would request ISP allow the consortium partners to decide on the lead bidder	As per tender condition.
6)	General	Price Variation Clause	Price Variation / Escalation Mechanism: Considering that the supply period would extend beyond a year, we request ISP to incorporate an appropriate Price Variation Clause. During the execution period, significant variations may occur in foreign exchange rates, semiconductor/module prices, electronic components, raw materials, logistics and other critical inputs, which may materially impact the cost of the finished inlays. We therefore request that an objective and mutually acceptable price variation mechanism be incorporated, covering material changes in foreign exchange rates and the prices of key imported and domestic inputs, from an agreed base date up to the date of supply.	Please refer Broad and Common point no. 8.
7)	General	Price matching between Domestic Development Tender & Global Tender	We would request ISP to confirm if there is an xx price which is LI in the Domestic Development Tender and XX+ L1 price quoted in the Global Tender. Will the global bidder have to match the L1 price of the Domestic Development Tender or vice versa? In case the domestic bidder has the match the L1 price of the global bidder what will be the basis of calculation. We request ISP to consider the INR price be linked to the evolving USD/ Euro exchange rates during the tenure of the contract	Not related to this PQB.
8)	General	Timelines for execution of the project	We would request ISP to confirm the timelines for the procurement of the entire quantity of the inlays	The tendered quantity of inlays is defined for the three year requirement.
9)	General	Request for extension for PQB submission	We would request ISP to kindly extended submission	Please refer Broad and Common point no. 4.

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		date	date of the PQB till 4th week of October	

19. RRP Electronics Ltd. – Mumbai (vide e-mail dt.31.08.2026 06.09 PM)

Sr. No.	Tender Section & Clause No. & Pg. No., if any	Tender Clause / Topic	Query of the firm	Reply
1)	Page 5 of 39 — Section II, Cl. 1(a)	Bidder should have manufactured and supplied at least 8.213 million sheets of Smart Cards (1-up) OR 4.107 million sheets of Inlays (2-ups) 'in any one of the last five years' ending 31.03.2025.	Please confirm that this threshold quantity must be achieved within a SINGLE financial/calendar year among the last five years, and is not to be read as a cumulative total supplied across the five-year period.	Please refer Broad and Common point no. 1.
2)	Page 5 of 39 — Section II, Cl. 1(a)	Smart Card experience (1-up, 8.213M sheets) is treated as an alternative, equivalent qualifying route to Inlay experience (2-ups, 4.107M sheets).	Please confirm Smart Card manufacturing experience is considered fully equivalent to e-passport Inlay experience for eligibility purposes, notwithstanding the differing substrate, lamination and durability requirements (e.g., ICAO MRTD Ver 3.2) specific to passport booklets.	Please refer Broad and Common point no. 1.
3)	Page 5 of 39 — Section II, Cl. 1(b)(iii)	Bidder (sole bidder/any consortium member) must have prior experience in products having Common Criteriacertified elements (chip and/or OS), evidenced by copies of the relevant CC certificate.	Please clarify whether individually-held CC certificates previously obtained by a chip vendor (for the chip) and/or an OS vendor (for the OS) on OTHER programmes are acceptable as documentary evidence of 'prior experience' at PQB stage — as distinct from the India-specific composite EAL5+ certification under Cl. 9(a)-(b), which is to be furnished later at the pre-production stage.	Please refer Broad and Common point no. 3.
4)	Page 31 of 39 — Annexure-III, Item A.3	'Machine Capability' is to be calculated 'as per demonstrated finished output quantity per hour' during the CVT trial.	Please clarify whether the minimum annual capacity of 4.107 million sheets/year will be assessed by extrapolating a single machine's demonstrated hourly output, or the aggregate output of all listed machines — and over how many working days/shifts per year this extrapolation will be based.	Demonstrated finished output quantity per hour during capacity verification process.

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5)	Page 6-7 of 39 — Note-8, Consortium Cl. 2(i)	A Consortium can have a maximum of 3 members; 'any member including Chip Manufacturer as well as OS manufacturer/developer cannot be a part of Multiple Consortium.'	Given the limited number of globally established CC EAL5+-certified secure-chip and passport-OS vendors, this restriction could materially limit the number of viable consortium combinations able to bid. Kindly clarify the intent, and confirm whether the restriction is applied strictly per legal entity (i.e., whether a vendor's regional subsidiary/affiliate is treated as the 'same' member), so bidders can structure consortia accordingly.	Query is not clear.
6)	Page 7 of 39 — Note-8, Consortium/IV Cl. 2(iii), read with Page 6, Note-7(ii)	Cl. 2(iii): 'An organization...cannot participate in more than 1 bid.' Separately, Note-7(ii) contemplates a bidder participating in BOTH the Global PQB Tender (No.17) and the Domestic Development PQB Tender (No.16), with a fall clause applying if both are won.	Please confirm that the 'not more than 1 bid' restriction applies only WITHIN this Global PQB Tender No.17/2026-27, and does not conflict with a bidder's ability to simultaneously participate in the separate Domestic PQB Tender No.16, as contemplated by Note-7(ii).	Please refer Broad and Common point no. 5.
7)	Page 7 of 39 — Consortium, in Cl. 2(iv)-(v)	Consortium members must enter into a duly notarized Consortium Agreement conveying intent to form the consortium.	Please confirm whether the Consortium Agreement (Annexure-IV) must be fully executed and notarized prior to PQB submission, or whether it may be submitted in draft/unsigned form at PQB stage, with final notarized execution required only upon shortlisting for the techno-commercial bid.	The Consortium Agreement (Annexure-IV) must be fully executed and notarized prior to PQB submission.

Subject: Queries of Prospective Bidders and reply thereof, w.r.t. The Global PQB Tender No. 17/2026-27 Dated: 06.08.2026 floated by India Security Press – Nashik (a unit of SPMCL) for 'Pre-Qualification Bid (PQB) tender for Procurement of 30.8 million sheets of ICAO Compliant Electronic Contactless Inlays (in 2 ups) along with its operating system for Indian e-Passport Booklets'.

20. Seshasaai Technologies Limited. – Mumbai (vide e-mail dt.31.08.2026 05.49 PM)

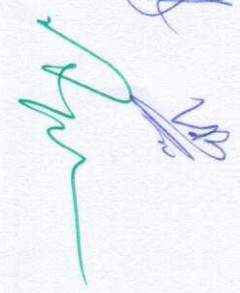
Sr. No.	Page No.	Clause No.	Text as per the PBQ	Query / Suggestion	ISP Reply
1	5	1 b (iii) (iii)	The manufactured Inlays (Samples with minimum 125 pcs in 2 ups) shall be carried to ISP-Nashik for machine trial and lab testing to check its suitability.	Please provide Product (Inlay) Specifications for Samples Creation during ISP's CVT visit.	Shall be provided at techno-commercial tender.
2	5	1 b (iii) (iii)	The manufactured Inlays (Samples with minimum 125 pcs in 2 ups) shall be carried to ISP-Nashik for machine trial and lab testing to check its suitability.	Testing of Inlays produced - please suggest which all tests would be conducted.	As per tender conditions.
3	5	1 b (iii) (iii)	The manufactured Inlays (Samples with minimum 125 pcs in 2 ups) shall be carried to ISP-Nashik for machine trial and lab testing to check its suitability.	Support of LDS1 is mandatory and LDS2 is optional. Please provide clarity on below mentioned optional points from LDS2: a- Is storage of Travel Records being considered at application layer? b- What about Visa and Biometric records? This will largely impact the implementation in all aspects, hence, please clarify.	Not related to PQB, and shall be elaborated in techno-commercial tender, if required.
4	5	1 b (iii) (iii)	The manufactured Inlays (Samples with minimum 125 pcs in 2 ups) shall be carried to ISP-Nashik for machine trial and lab testing to check its suitability.	CLA for Chaining APDU for PACE(0x10) is not available in 16695_1_2022. a- How is it going to be managed? b- Will 16695_1_2022 specification adapt this for PACE Chaining?	Not related to PQB, and shall be elaborated in techno-commercial tender, if required.

5	5	1 b (iii) (iii)	The manufactured Inlays (Samples with minimum 125 pcs in 2 ups) shall be carried to ISP-Nashik for machine trial and lab testing to check its suitability.	PACE supports many algorithms which is managed using "PACE OID" a- Please provide clarity on supported PACE OIDs required at application layer.	
6	5	1 b (iii) (iii)	The manufactured Inlays (Samples with minimum 125 pcs in 2 ups) shall be carried to ISP-Nashik for machine trial and lab testing to check its suitability.	Below mentioned details are needed in CRYPTOGRAPHY section: a- RSA with which key size? b- Which ECC Curves to be implemented? c- Please suggest about AES with Key size and modes? d- Details related to SHA algorithms, which to support?	Not related to PQB, and shall be elaborated in techno-commercial tender, if required.
7	3, 4, 6, 8 and 14	Point 5 on Page 3, Point 10 on Page 4, Point Note-7 ii on Page 6, Point 2 on Page 8 and Point 1.2 on Page 14.	Drafts as per PQB.	These Declarations are to be signed by Lead Member only or Consortium Partner also, if any. If it is to be signed by Consortium Partner also, can Lead Member and Consortium Partner sign on a same document?	Signed by the lead member who having the power of attorney to sign the tender document.
8	9	9a to 9f	Drafts as per PQB.	Declarations 9a to 9f are to be submitted individually for each point or the points can be clubbed in 1 Declaration, please clarify. Also, if it is to be signed by Lead Member only or Consortium Partner also, if any. If it is to be signed by Consortium Partner also, can Lead Member and Consortium Partner sign on a same document?	Signed by the lead member who having the power of attorney to sign the tender document.

13	28	Section 3	If the 'Bidder/Contractor', before award or during execution has committed a transgression through a violation of Section 2, above or in any other form such as to put their reliability or credibility in question, the Principal is entitled to disqualify the 'Bidder/Contractor' from the tender process or take action as per the procedure mentioned in the "Guidelines on Banning of business dealings".	We recommend deleting "or in any other form such as to put their reliability or credibility in question", as the same is vague and subjective. Any disqualification should ideally be linked to a specific violation of the Integrity Pact or applicable guidelines.	As per tender condition.
14	28	Section 4 (2)	If the Principal has terminated the contract according to Section 3, or if the Principal is entitled to terminate the contract according to Section 3, the Principal shall be entitled to demand and recover from the Contractor liquidated damages of the Contract value or the amount equivalent to Performance Bank Guarantee.	We request that the damages shall be recoverable only to the extent of the actual loss suffered by ISP and that such recovery shall not exceed the amount of the Performance Bank Guarantee.	As per tender condition.







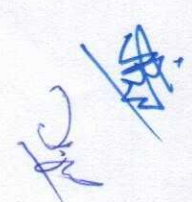













			Capacity of manufacturing of ICAO Compliant Electronic Contactless Inlays for e-Passports in 2 ups by assembling the chip, antenna and seamless integration of the same on suitable substrate on same plane. Manufacturing of the same should be demonstrated, with producing of Dummy Inlays in 2 ups by assembling the chip, antenna and seamless integration of the same on suitable substrate on same plane/sheet i.e. Fusing of Antenna on suitable substrate and permanent bonding of the Chip & Antenna by means of resistance welding/ arc welding etc. on same substrate as well as further lamination/ sealing mechanism of the suitable substrate to form a permanent packaging.	An inlay can be manufactured using two different approaches. The first approach uses a semiconductor packaged in industrial packaging, which is commonly used for most citizen ID cards and passports. The second approach involves directly placing the semiconductor die onto the antenna, which is standard practice for RFID tags, this approach is also used in a few passport projects. Would you also accept the bare-die-on-antenna manufacturing process for this tender?	As per tender condition.
15	31	Annexure III, Point No. 4			
16	37	14, Indemnification	All consortium members of this agreement shall fully indemnify, hold harmless and defend ISP and its officers etc., from and against all claims, liabilities, suits, damages including any criminal liability due to false declaration by the consortium members with regard to this Agreement (or) Tender transaction (or) Project (or) contract etc., caused due to negligence/commission/omission of the any of the consortium members (or) its employees and agents including representatives (or) sub-contractors (or) any other person claiming (or) any other person claiming under this tender (or) under the applicable laws of India.	We suggest that the indemnity obligations of each Consortium Member be limited to claims, losses and liabilities arising from or relating to its respective scope of work and responsibilities under the Consortium Agreement and the Contract. We further suggest that an appropriate cap on liability be included, with the liability of the Consortium Members being capped at the value of the Contract. We further recommend that indirect, incidental, consequential, special and exemplary damages be excluded from the scope of liability.	As per tender condition.
17	35-39	Annexure IV	Consortium Agreement.	Signing of Consortium Agreement as per Annexure IV - is it to be Notarized & submitted in Original.	Yes